

Please add the following new claims to the application:

- 23. The polishing solution for metal according to claim 12, which comprises an oxidizing agent, an oxidized-metal dissolving agent, a first protective-film forming agent, a second protective-film forming agent different from the first protective-film forming agent, and water.
24. The polishing solution for metal according to claim 13, which comprises an oxidizing agent, an oxidized-metal dissolving agent, a first protective-film forming agent, a second protective-film forming agent different from the first protective-film forming agent, and water.
25. The polishing solution for metal according to claim 11, which is used to polish a metal containing at least any one of copper, a copper alloy, a copper oxide and a copper alloy oxide.
26. The polishing solution for metal according to claim 15, which is used to polish a metal containing at least any one of copper, a copper alloy, a copper oxide and a copper alloy oxide.
27. The polishing solution for metal according to claim 11, which substantially does not contain any abrasive grains.
28. The polishing solution for metal according to claim 15, which substantially does not contain any abrasive grains.

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29. A polishing method comprising polishing a metal film formed on the surface of a polishing object, in the polishing solution for metal according to claim 11, to remove the metal film.

30. A polishing method comprising polishing a metal film formed on the surface of a polishing object, in the polishing solution for metal according to claim 15, to remove the metal film.

31. The polishing method according to claim 30, wherein said metal film contains at least any one of copper, a copper alloy, a copper oxide and a copper alloy oxide.

32. The polishing method according to claim 30, wherein:

said polishing object has a multi-layer film having a metal layer containing at least any one of copper, a copper alloy, a copper oxide and a copper alloy oxide; and

the polishing method is a method of removing at least part of the metal film from the multi-layer film.

33. The polishing method according to claim 30, wherein said polishing solution for metal substantially does not contain any abrasive grains.--

REMARKS

Prior to calculation of the Filing Fee, Applicants have amended their claims in order to delete multiple dependency. Moreover, in the view of the deletion of multiple dependency, Applicants have added new claims 23-33 to the application.